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SEMICONDUCTOR



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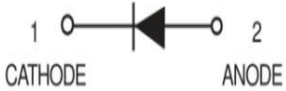

1SS400CS-MS

Product specification

General Features

- We declare that the material of product compliance with
- RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring
- unique site and control change requirements; AEC-Q101
- qualified and PPAP capable.
- Extremely small surface mounting type.
- High Speed.
- High reliability.

Reference News

PACKAGE OUTLINE	Pin Configuration	Marking
 <hr/> <p>SOD-923</p>		

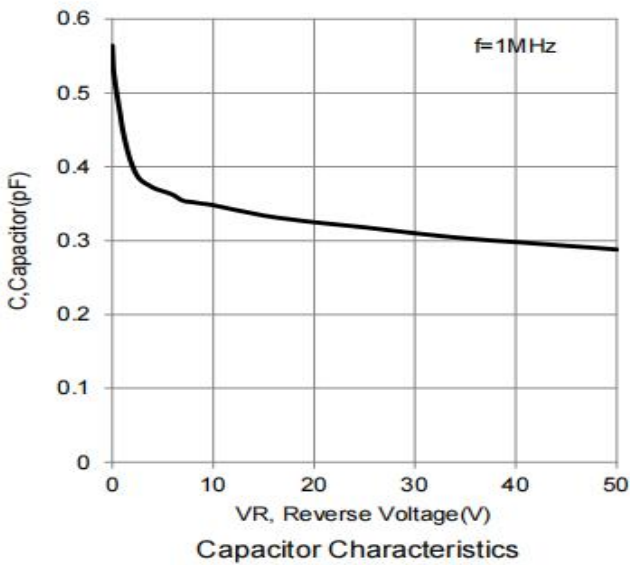
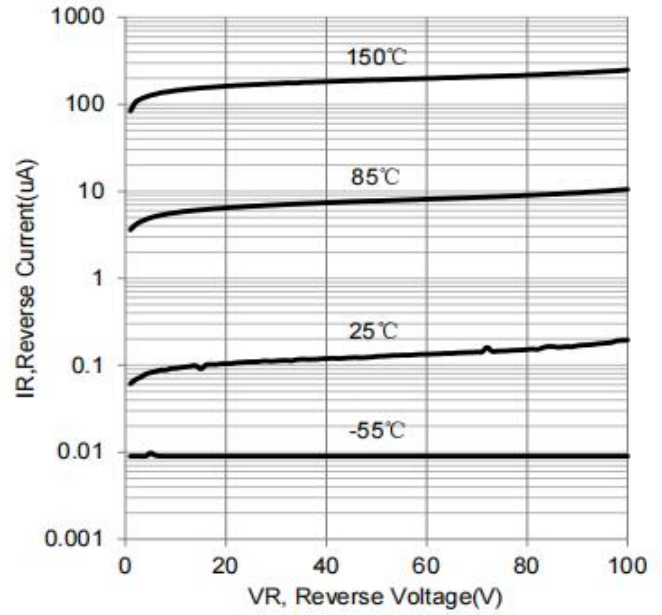
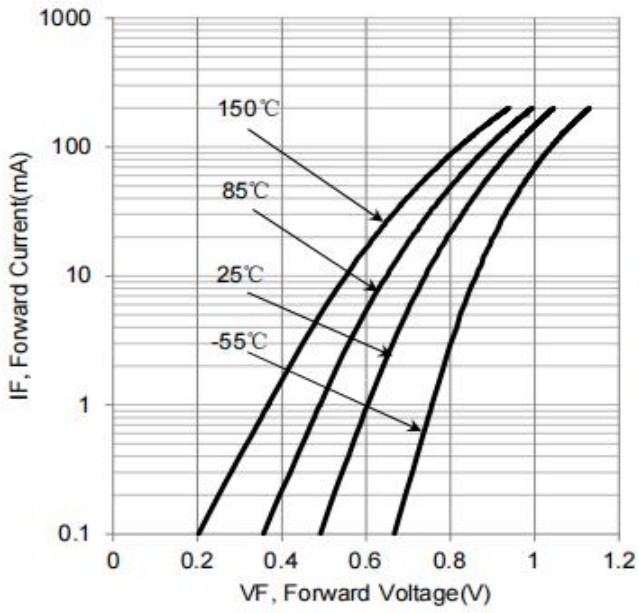
MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Peak reverse voltage	VRM	100	V
DC reverse voltage	VR	85	V
Peak forward current	IFM	300	mA
Mean rectifying current	IO	100	mA
Surge current (1s)	I _{surge}	500	mA
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55~+125	°C

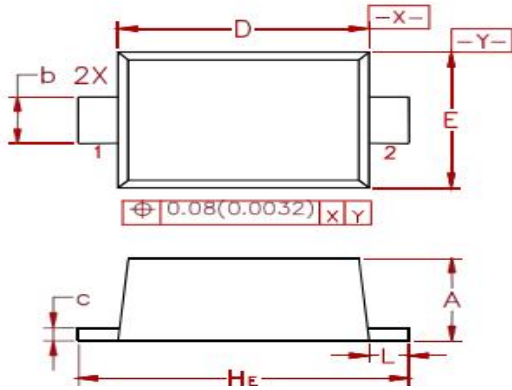
ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Forward voltage (IF =100mA)	VF	-	-	1.2	V
Reverse current (VR =80V)	IR	-	-	0.1	pA
Capacitance between terminals (VR =0.5V , f=1MHz)	CT	-	0.72	3	pF
Reverse recovery time (VR =6V , IF =10mA , RL =100Ω)	trr	-	-	4	nS

ELECTRICAL CHARACTERISTICS CURVES

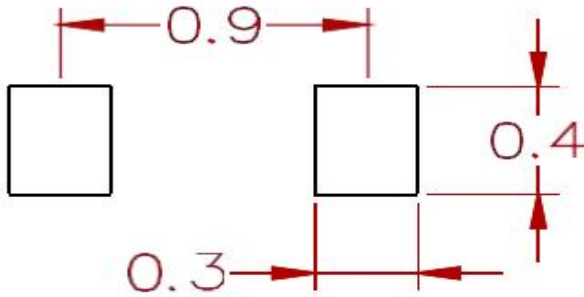


PACKAGE MECHANICAL DATA



Dim	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.36	0.40	0.43	0.014	0.016	0.017
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
HE	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

Suggested Pad Layout



Dimensions: Millimeters

REEL SPECIFICATION

P/N	PKG	QTY
1SS400CS-MS	SOD-923	8000

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